

REMARKS

Claims 86-89 were rejected under §112, first paragraph. Claim 86 has been amended so that the metallic frame is in the side of the second surface and surrounds the metallic post. Support for the recitation of the metallic frame is found in Figures 12-13. The frame is element 25. The supporting text is found on pages 126 and 144. Reconsideration and withdrawal of the rejection are respectfully requested.

Claims 1-42, 44, and 55-85 are canceled and withdrawal of the rejections of these claims is requested.

Claims 43, 45, and 50-54 were rejected as unpatentable over NAKAMURA et al. 6,372,547 in view of HSUAN et al. 6,252,300; claims 46-49 were rejected as unpatentable further in view of NAKATANI et al. 6,038,133; and claims 50-51 were further rejected as unpatentable in view of NAKAMURA et al., HSUAN et al. and KITAZAWA et al. 6,057,600. Claim 43 has been amended and reconsideration and withdrawal of the rejection are respectfully requested.

Amended claim 43 provides that the interconnection board has a multilevel insulating resin layer and a multilayer wiring layer therein. NAKAMURA et al. disclose an interconnection board 3 of semiconductor that does not have a multilevel insulating resin layer or a multilayer wiring layer therein. The undersigned is informed by the applicant that since NAKAMURA et al. do not disclose the multilevel insulating resin layer and multilayer

wiring layer, the combination of NAKAMURA et al. with the other references could not suggest the present invention to one of skill in the art.

Claims 86-88 were rejected as unpatentable over TSUKAMOTO in view of MAENO et al. 6,222,738 and HAYASHI. Reconsideration and withdrawal of the rejection are respectfully requested.

Amended claim 86 provides that the semiconductor chip is mounted in a side of the first surface of a multilayer interconnection board, the first surface being opposite and spaced from a second surface of the board, and that the metallic post and metallic frame are on the second surface with the external electrode pad from which the metallic post protrudes. By contrast, TSUKAMOTO discloses that the semiconductor chip, metallic post and metallic frame are all on the same side. The undersigned is informed by the applicant that since TSUKAMOTO does not disclose that the semiconductor chip is on side opposite the metallic post and metallic frame, the combination of TSUKAMOTO with the other references could not suggest the present invention to one of skill in the art.

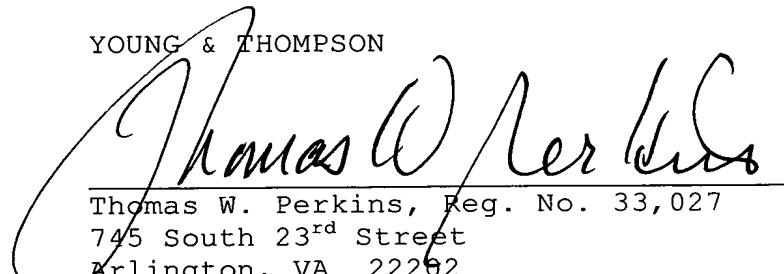
In view of the present amendment and the foregoing remarks, it is believed that the present application has been placed in condition for allowance. Reconsideration and allowance are respectfully requested.

The Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment or credit any overpayment

to Deposit Account No. 25-0120 for any additional fees required  
under 37 C.F.R. § 1.16 or under 37 C.F.R. § 1.17.

Respectfully submitted,

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